PCN Number:	20160923000	PCN	Date:	Sept. 30,2016	
	r LM5112/LM5112-Q1		. 2001	1 2000 20/2010	
Customer Contact:	PCN Manager		Dept:	Quality Services	
Change Type:					
Assembly Site	Design		Wafe	er Bump Site	
Assembly Process	☐ Data She	et		er Bump Material	
Assembly Material		ber change		er Bump Process	
Mechanical Specif				er Fab Site	
Packing/Shipping/	Labeling Test Proc	ess		er Fab Materials	
	N - L!£! L! -	m Detelle	Wafe	er Fab Process	
Notification Details					
Description of Change: Texas Instruments Incorporated is announcing an information only notification.					
The product datasheet(s) is updated as seen in the change revision history below:					
L ME440 L ME440 O4				TEXAS INSTRUMENTS	
LM5112, LM5112-Q1 SNVS234C - SEPTEMBER 2004-REV	ISED SEPTEMBER 2016			www.ti.com	
Changes from Revision B (April 2006) to Revision C Page					
Added ESD Ratings table, Feature Description section, Device Functional Modes, Application and Implementation     Section, Review Supply Recommendations section, Levelt section, Device and Description Supply Recommendations					
section, Power Supply Recommendations section, Layout section, Device and Documentation Support section, and Mechanical, Packaging, and Orderable Information section					
Changed values in the <i>Thermal Information</i> table to align with JEDEC standards					
- <del></del>					
Device Family		Chang	je From:	Change To:	
LM5112/LM5112-Q1		SNVS		SNVS234C	
These changes may be reviewed at the datasheet links provided. http://www.ti.com/lit/ds/symlink/lm5112.pdf					
http://www.ti.com/lit/o	ds/symlink/lm5112.pdf	·			
http://www.ti.com/lit/d	ds/symlink/lm5112.pdf	·			
Reason for Change:	ds/symlink/lm5112.pdf lect device characteristics.	·			
Reason for Change: To more accurately ref			ility (pos	sitive / negative):	
Reason for Change: To more accurately ref Anticipated impact of	lect device characteristics.	uality or Reliab			
Reason for Change: To more accurately ref Anticipated impact of No anticipated impact, to the actual device.	lect device characteristics.	uality or Reliab			
Reason for Change: To more accurately ref Anticipated impact of No anticipated impact, to the actual device.	lect device characteristics.  on Fit, Form, Function, Q  This is a specification char	uality or Reliab			
Reason for Change: To more accurately ref Anticipated impact of No anticipated impact, to the actual device. Changes to product	lect device characteristics.  on Fit, Form, Function, Q  This is a specification char	uality or Reliab			
Reason for Change: To more accurately ref Anticipated impact of No anticipated impact, to the actual device. Changes to product None. Product Affected:	lect device characteristics.  In Fit, Form, Function, Q  This is a specification char  Identification resulting f	uality or Reliab	nt only. Th	nere are no changes	
Reason for Change: To more accurately ref Anticipated impact of No anticipated impact, to the actual device. Changes to product None.	lect device characteristics.  on Fit, Form, Function, Q  This is a specification char	uality or Reliab	nt only. Th		

or your local Field Sales Representative.

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